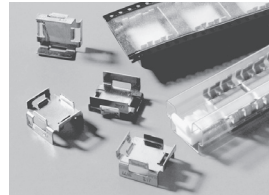


BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



217 SERIES SURFACE MOUNT HEAT SINKS

D2PAK; TO-220; SOT-223; SOL-20

Compatible with surface mount technology (SMT) automated production techniques for ease of assembly and a variety of soldering methods, these heat sinks allow greater packaging densities and reduction in PC-board area, increasing the power dissipation of surface mount devices (SMDs) while maintaining and improving manufacturers' component thermal specifications.

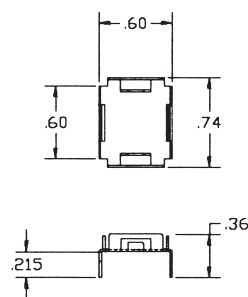
FEATURES AND BENEFITS

- No interface material is needed
- Copper with matte tin plating for improved solderability and assembly
- Both the component and the heat sink are installed on the PC-board utilizing standard SMT assembly equipment for "Tape & Reel" and "Tube" formats
- EIA standards and ESD protection are specified
- Can be used with water soluble or no clean SMT solder creams or other pastes

Footprint Standard P/N	Height Above PC Board in. (mm)	Dimensions in. (mm)	Package Format	Package Quantity	Thermal Performance at Typical Load	
					Natural Convection	Forced Convection
217-36CTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Bulk	1	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tube	20	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTRE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tape & Reel	250	55°C @ 1W	16.0°C/W @ 200 LFM

Material: Copper, Matte Tin Plated

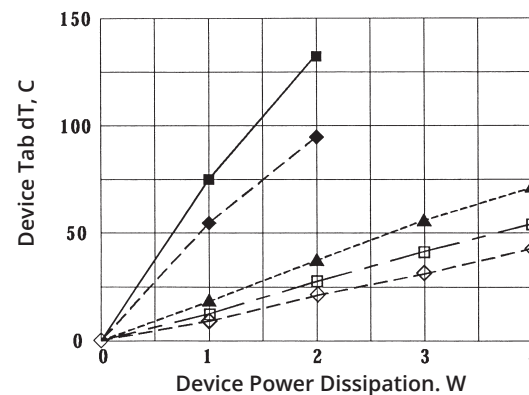
MECHANICAL DIMENSIONS



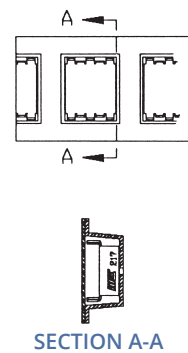
217-36CT6

Dimensions: in.

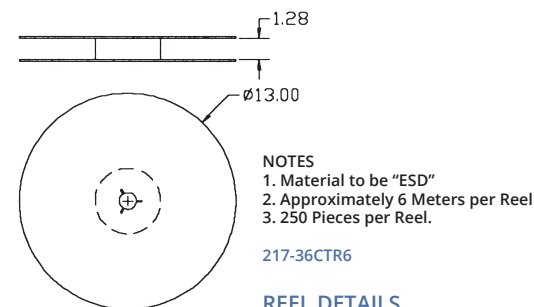
THERMAL PERFORMANCE 6 LAYER BOARD, D' PAK 125°C LEAD, 40°C AMBIENT



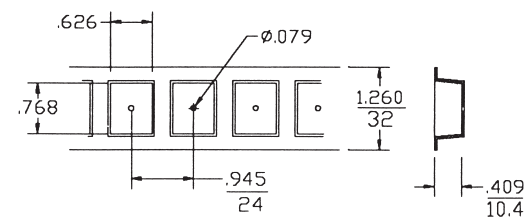
KEY: ■ Device only, NC ◆ Device + HS, NC ▲ Device + HS, 100 lfm
□ Device + HS, 200 lfm ◇ Device + HS, 300 lfm



SECTION A-A



REEL DETAILS

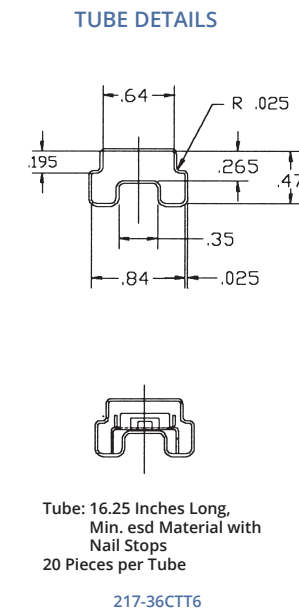


TAPE DETAILS

SURFACE MOUNT HEAT SINKS

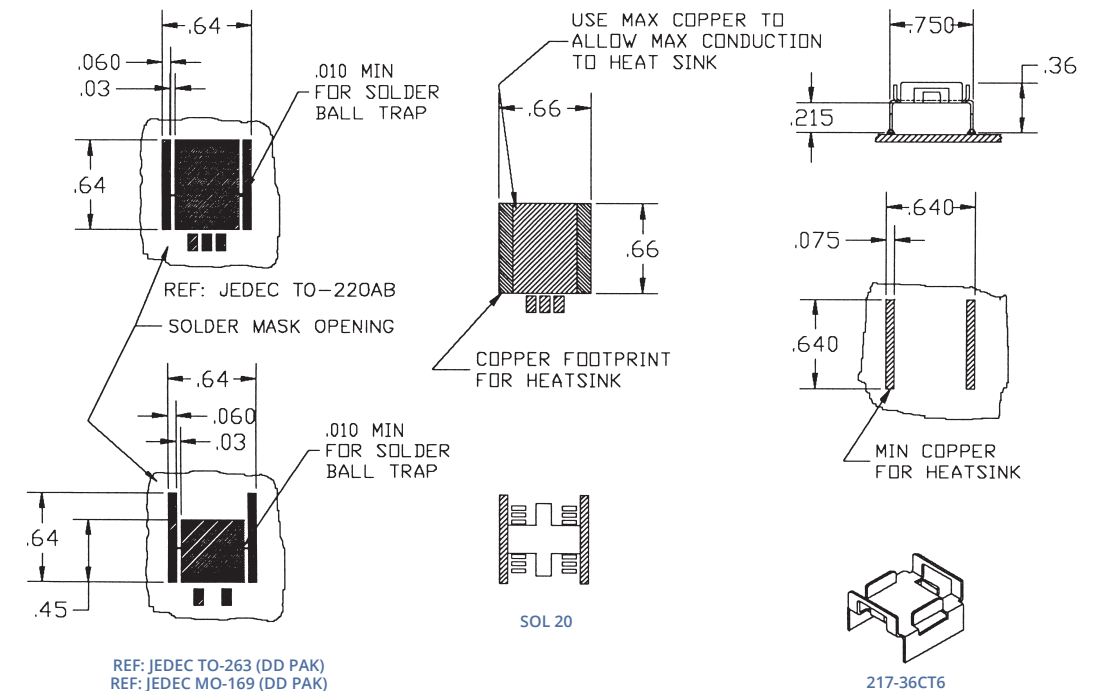
217 SERIES

MECHANICAL DIMENSIONS



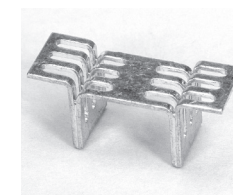
Dimensions: in.

BOARD LAYOUT RECOMMENDATIONS



218 SERIES SURFACE MOUNT HEAT SINK

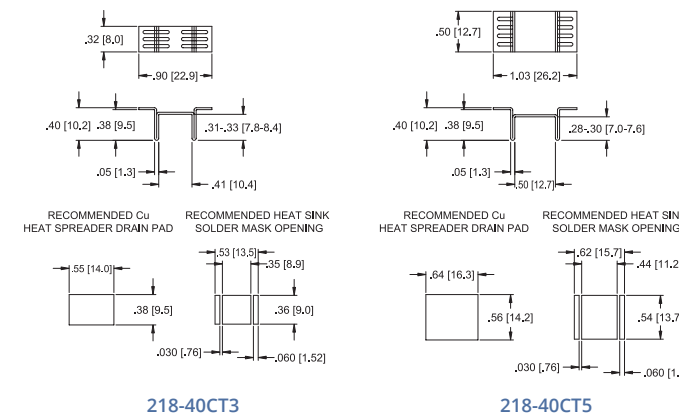
SMT Devices



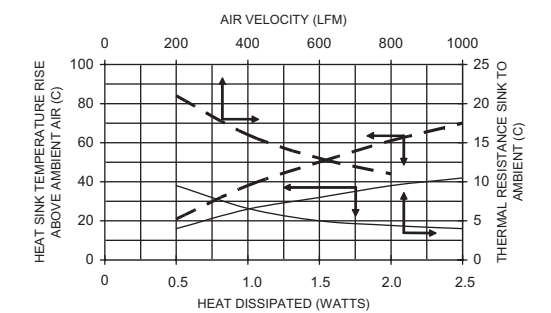
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
218-40CTE3	.40 (10.2)	.90 (22.9) x .315 (8.0)	62°C rise @ 2W	21°C/W @ 200LFM
218-40CTE5	.40 (10.2)	1.03 (26.2) x .50 (12.7)	62°C rise @ 2W	21°C/W @ 200LFM

Material: Copper, Matte Tin Plated

MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



Solid line = 218-40CT5 Dashed Line = 218-40CT3

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Wakefield Thermal:](#)

[217-36CTE6](#)